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## High performance In<sub>2</sub>O<sub>3</sub> nanowire transistors using organic gate nanodielectrics

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We report the fabrication of high performance nanowire transistors (NWTs) using  $In_2O_3$  nanowires as the active channel and a self-assembled nanodielectric (SAND) as the gate insulator. The SAND-based single In<sub>2</sub>O<sub>3</sub> NWTs are controlled by individually addressed gate electrodes. These devices exhibit *n*-type transistor characteristics with an on-current of  $\sim 25 \ \mu$ A for a single In<sub>2</sub>O<sub>3</sub> nanowire at  $2.0V_{ds}$ ,  $2.1V_{gs}$ , a subthreshold slope of 0.2 V/decade, an on-off current ratio of 10<sup>6</sup>, and a field-effect mobility of  $\sim$ 1450 cm<sup>2</sup>/V s. These results demonstrate that SAND-based In<sub>2</sub>O<sub>3</sub> NWTs are promising candidates for high performance nanoscale logic technologies. © 2008 American Institute of Physics. [DOI: 10.1063/1.2937111]

Recently, there have been several studies of nanowire transistors (NWTs) aimed at achieving high performance and reliable transistor response characteristics. One potential application of NWTs is to replace polysilicon (poly-Si) or amorphous-silicon ( $\alpha$ -Si) thin-film transistors (TFTs) currently used in displays, sensors, solar cells, and other optoelectronic devices.<sup>1-4</sup> NWTs have several attractions versus poly-Si TFTs and  $\alpha$ -Si TFTs, in terms of high mobility, optical transparency (for large band-gap nanowires), and mechanical flexibility. These characteristics could allow higher frequency TFT operation and enable flexible/transparent electronics. For instance, future light-emitting diode-based displays could be integrated with optically transparent windows and/or operate at far lower power by enhancing the pixel aperture ratio. The latter parameter can be increased, for a given pixel spacing, by either stacking transparent TFT layers or significantly reducing the area required for the drive transistor. However, consideration of the NW-based device performance metrics reported to date reveals that there is significant room for improvement before NWT-derived driving and switching elements can be assembled into useful electronic circuits. Among several possible semiconducting nanowire materials, In<sub>2</sub>O<sub>3</sub> is one of the most promising because of its easy access, chemical stability, and wide band gap (3.6 eV).<sup>5-8</sup> This combination of unique materials properties and the fundamental advantages of the quasi-onedimensional nanowire electronic structure underscore the potential of In<sub>2</sub>O<sub>3</sub> NWTs for advanced electronic applications requiring high transistor performance, optical transparency, and mechanical flexibility. In this study, we report significantly enhanced performance metrics for NWTs consisting of individual In<sub>2</sub>O<sub>3</sub> nanowires as channels combined with a self-assembled organic nanodielectric<sup>9</sup> (SAND) as the gate insulator. The present SAND-based In2O3 NWTs demonstrate considerable advances in performance over previously reported NWTs employing In<sub>2</sub>O<sub>3</sub> or other mid/wide bandgap NWTs, especially in terms of greatly improved field-effect mobility and high on-current densities.<sup>10–16</sup>

A cross-sectional view of the present NWT structure is shown in Fig. 1(a). Starting with a Corning 1737 glass substrate coated with a 500 nm SiO<sub>2</sub> buffer layer, individually addressable, transparent indium tin oxide (ITO) bottom-gate electrodes were deposited by ion-assisted deposition and photolithographically patterned. This individually addressable gate structure affords a high level of circuit integration

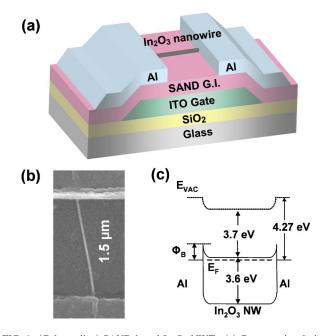


FIG. 1. (Color online) SAND-based In<sub>2</sub>O<sub>3</sub> NWTs. (a) Cross-sectional view of the device structure. (b) Top-view FE-SEM images of the device region. Scale bar=1.5  $\mu$ m. (c) Source/nanowire/drain cross-section band diagram at  $V_{gs}=0$  V.

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using NWTs. The SAND gate dielectric ( $\sim 15$  nm) was then deposited using a layer-by-layer wet chemical process and provides a large capacitance of  $\sim 180 \text{ nF/cm}^2$  with an electric breakdown field of ~7 MV/cm. The conformal SAND provides excellent edge coverage, resulting in low interlayer leakage in the gate and source-drain overlap regions. This high performance gate dielectric allows the channel potential to be modulated at relatively low gate voltages. The  $In_2O_3$ nanowires, which were synthesized via laser ablation,<sup>10</sup> are not intentionally doped, but are believed to be lightly *n* type. The nanowires were suspended in isopropanol solution and then deposited onto the patterned substrates. Aluminum source/drain electrodes ( $\sim$ 130 nm) were then deposited by electron-beam evaporation. Figure 1(b) shows a fieldemission scanning electron (FE-SEM) micrograph of a single In<sub>2</sub>O<sub>3</sub> nanowire confined between the source/drain electrodes. The diameter and length of the  $In_2O_3$  nanowires are 20 nm and 1.5  $\mu$ m, respectively. The corresponding band diagram (source/NW/drain cross section for an aluminum contact structure) for a NWT at  $V_{gs}=0$  V is shown in Fig. 1(c). The electron affinity of In<sub>2</sub>O<sub>3</sub> ( $\chi_{In_2O_3}$ ) is 3.7 eV, and the bulk Fermi level position for moderate doping is estimated to be  $(E_e - E_f) = 0.6 \text{ eV}$ , yielding an effective work function  $\Phi_{\text{In}_2\text{O}_2}$ =4.54 eV for *n*-type material. Al source/drain contacts  $(\Phi_{A1}=4.28 \text{ eV})$  are therefore expected to form relatively low interface barrier heights to n-type In<sub>2</sub>O<sub>3</sub> NWs.

The present  $In_2O_3$  NWTs exhibit excellent *n*-type transistor characteristics. All the NWT performance parameters reported here correspond to devices treated with ozone on the nanowire regions<sup>17</sup> with  $O_2$  plasma polishing on the source-drain contact region to maximize device performance. Figure 2(a) shows the drain current versus gate-source voltage  $(I_{ds}-V_{gs})$  characteristics for a representative single In<sub>2</sub>O<sub>3</sub> NWT, on both linear and semilog scales, as well as the measured field-effect mobility inferred from the transconductance  $(g_m)$  at the respective gate voltage. The device exhibits a subthreshold slope (S) of 0.2 V/decade, an on-off current ratio  $(I_{\rm on}/I_{\rm off})$  of 10<sup>6</sup>, and a threshold voltage  $(V_{\rm th})$  of 0.0 V. The drain current versus drain-source voltage  $(I_{ds}-V_{ds})$  characteristics of a representative NWT are shown in Fig. 2(b). These devices exhibit no evidence of saturation of the  $I_{ds}$  in the investigated potential bias range and exhibit an  $I_{\rm on} \sim 25 \ \mu A$  for the single  $In_2O_3$  nanowire at  $V_{\rm ds} = 2.0 \ V$ ,  $V_{\rm gs}$ =2.1 V, respectively. Although a possible mechanism for the nonideal  $I_{ds}$ - $V_{ds}$  curve at high gate voltages might be ascribed to nanowire body leakage, in fact the measured leakage current through the SAND layer is only 30-40 pA at 4 V, indicating negligible leakage current through the gate dielectric. In order to allow direct comparison to other reported transistor performance data, including other NWTs, Ion can be expressed in terms of a current density of  $\sim 8 \times 10^6$  A/cm<sup>2</sup>, assuming uniform current flow throughout the nanowire cross section. The current per unit channel width is greater than 1 mA/ $\mu$ m, considering only the diameter of the nanowire. Importantly, this current level for a single nanowire is sufficient to drive a  $176 \times 54 \ \mu m^2$  size AMOLED pixel at 300 cd/m<sup>2</sup> in current-generation electroluminescent technologies.

The field-effect mobility is extracted from the measured  $g_m$  and the calculated gate-to-channel capacitance  $(C_i = 2\pi\varepsilon_0 k_{\rm eff}L/\cosh^{-1}(1+t_{ox}/r))$  using  $\mu = dI_{\rm ds}/dV_{\rm gs}$  lated electrostatic screening lengths,<sup>20</sup> the characteristic length over which the bands bend at the metal-semiconductor (M-S) contact interface, as illustrated in Fig 1(c), is estimated to be ~30 nm. This characteristic length power of pownloaded 20 Nov 2008 to 128.46.220.88. Redistribution subject to AIP license or copyright; see http://apl.aip.org/apl/copyright.jsp

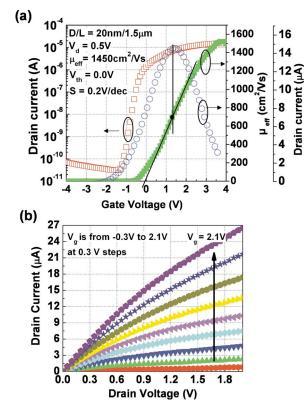


FIG. 2. (Color online) Measured characteristics of a representative SANDbased  $In_2O_3$  NWT. (a) Drain current versus gate-source voltage  $(I_{ds}-V_{gs})$ characteristics at  $V_d$ =0.5 V. Green, red, and blue data points correspond to linear-scale  $I_{ds}-V_{gs}$ , log-scale  $I_{ds}-V_{gs}$ , and and mobility  $\mu$ . (b) Drain current vs drain-source voltage  $(I_{ds}-V_{ds})$  characteristics for various values of  $V_{gs}$ (-0.3 to 2.1 V in 0.3 V steps).

SAND  $(k_{\text{eff}})$  is ~3.0, the device channel length (L) is  $\sim$ 1.5  $\mu$ m, and the radius (r) of the In<sub>2</sub>O<sub>3</sub> NW is 10 nm. The measured  $g_m$  at  $V_d = 0.5$  V, along with a Gaussian fit to the data, is illustrated in Fig. 3(a). The  $g_m$  peaks at ~5.87  $\mu$ S, at  $V_{g} \sim 1$  V, and falls off with increasing gate voltage. The corresponding  $\mu$  is plotted versus gate bias in Fig. 2(a) and varies from  $\sim 1450 \text{ cm}^2/\text{V} \text{ s to} \sim 300 \text{ cm}^2/\text{V} \text{ s}$  over the measured gate bias range. The peak mobility values of two other devices with from the same sample batch, with nominally identical structures, are  $\sim 1200$  and  $1170 \text{ cm}^2/\text{V}$  s The peak value, which is typically quoted as the mobility in comparable devices, significantly exceeds In<sub>2</sub>O<sub>3</sub> NW mobilities  $(\mu = 6.93 - 279 \text{ cm}^2/\text{V s})$  reported in other devices<sup>10-13</sup> and in single-crystal  $In_2O_3$  (~160 cm<sup>2</sup>/V s).<sup>18</sup> It is expected that the NW single-crystal nature along with the quasi-onedimensional electronic structure, which inhibits low-angle scattering, contributes to the very large FET mobility. In addition, the SAND gate dielectric has previously been found to enable high performance in other oxide NWs.<sup>19</sup>

Several aspects of the observed current-voltage characteristics can be attributed to the effects of the contacts. While an ideal long-channel metal-oxide-semiconductor field-effect transistor (MOSFET) model describes the low  $V_{\rm ds}$  data, the behavior at large  $V_{\rm ds}$  deviates from the ideal MOSFET model both in terms of the nonsquare law relationship versus  $V_{\rm gs}$ and the relatively large drain conductance. Based on calculated electrostatic screening lengths,<sup>20</sup> the characteristic length over which the bands bend at the metalsemiconductor (M-S) contact interface, as illustrated in Fig. 1(c), is estimated to be ~30 nm. This characteristic length

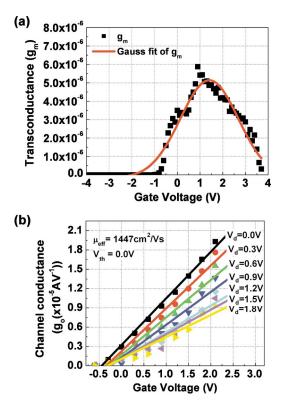


FIG. 3. (Color online) (a) Measured transconductance  $(g_m)$  at  $V_{\rm ds}$ =0.5 V, along with a Gaussian fit to the data. (b) Measured channel conductance  $(g_d)$  vs  $V_{\rm gs}$ , with various curves corresponding to steps in  $V_{\rm ds}$  from 0.0 to 1.8 V.

would be reduced by channel charge induced by the gate potential or due to donor doping, which typically arises from oxygen vacancies in metal-oxide semiconductors. For this range of barrier thicknesses, it is expected that the contact behavior would be dominated by thermionic-field emission,<sup>21</sup> which would yield a nonlinear current-voltage characteristic for the M-S contacts. A prior study on NW transistors indicated that the effects of such a barrier in series with the channel included a roll-off in transconductance with increasing gate bias,<sup>22</sup> comparable to that observed in the present study. Figure 3(b) shows the measured channel conductance  $(g_d)$  versus gate voltage for various values of  $V_d$ . Linear series/contact resistance effects, would be expected to result in a saturation of  $g_d$  with increasing  $V_g$ .<sup>23</sup> However, no saturation is observed, indicating that linear series resistance effects are not dominant factors in the current-voltage (I-V)characteristics over the present bias range. The curves in Fig. **3(b)** for low  $V_d$  values are somewhat superlinear, likely due to increasing conductance of the M-S contact barriers with increasing gate bias. These observations are consistent with the modest, but nonzero, M-S contact barrier illustrated in Fig. 1(c).

In conclusion, high performance, transparent NWTs have been fabricated using single  $In_2O_3$  nanowires as the active channel, a SAND layer as the gate insulator, alumi-

num as source-drain electrodes, and ITO as the gate electrode. The single  $In_2O_3$  NWTs were operated by individually addressable gate electrodes, which represents a significant advance toward circuit fabrication, and outstanding NWT device performance metrics were obtained using a SAND gate dielectric and proper processing of the  $In_2O_3$  nanowire. As a result, we achieved significantly enhanced  $In_2O_3$  NWT device performance and a significantly greater mobility than observed in poly-Si TFTs and  $\alpha$ -Si TFTs. Since it is desirable to obtain high  $\mu$  and a steep *S* to fabricate rapid-switching transistors and high-speed logic circuits, these results indicate that SAND-based  $In_2O_3$  NWTs can support the requirements of such devices.

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